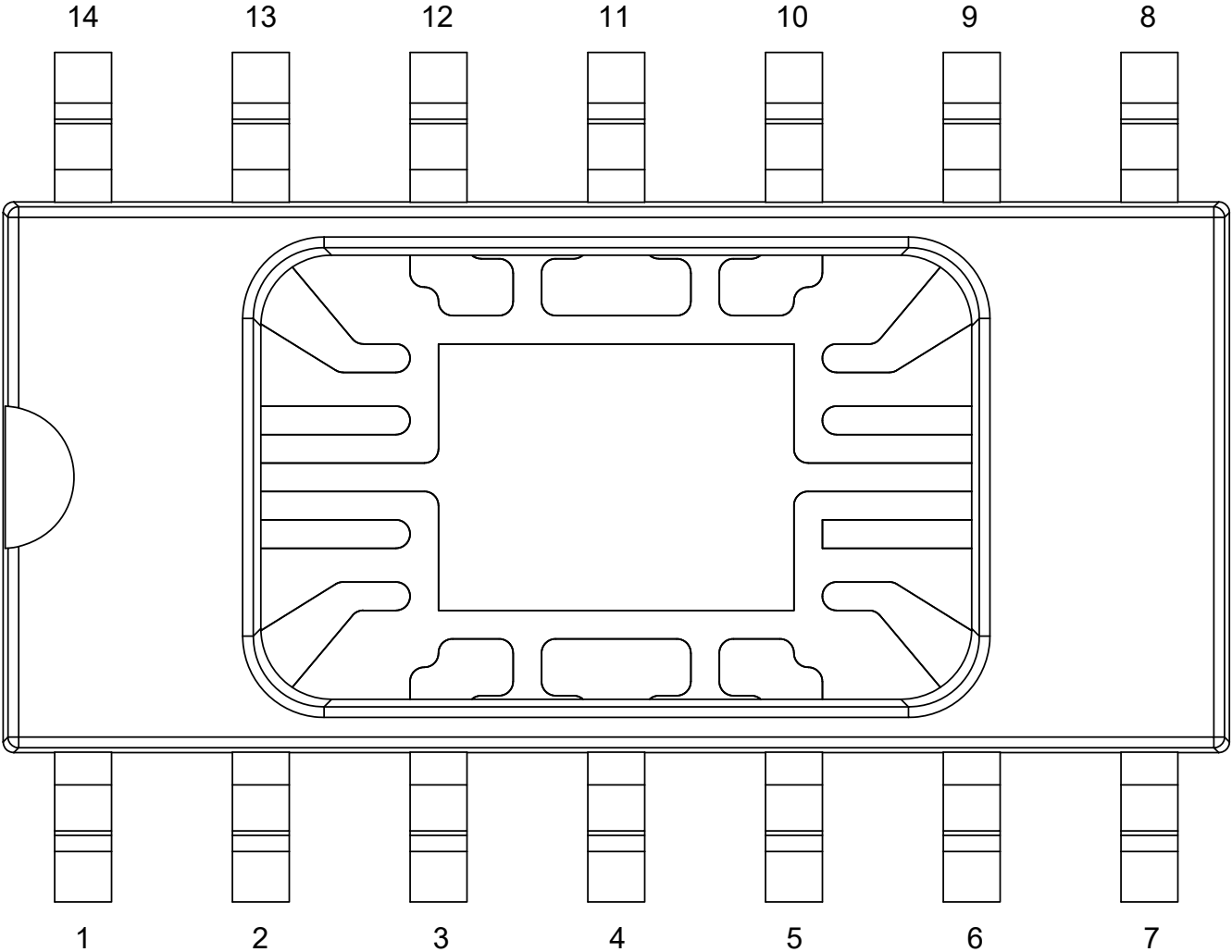



Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS: INCHES [MM].
- 2) PACKAGE CONFORMS TO JEDEC MS-012.
- 3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
- 4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
- 5) PLATING: NICKEL 100~300 MICRONS (2.5~7.6μM) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.

APPROVALS		DATE				
DRAWN	J. Hines	1/10/2017				
ENG	M. Hart	1/10/2017	SCALE		SIZE	DRAWING NO.
MFG			10:1	A	120114	REV
QA						A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 4

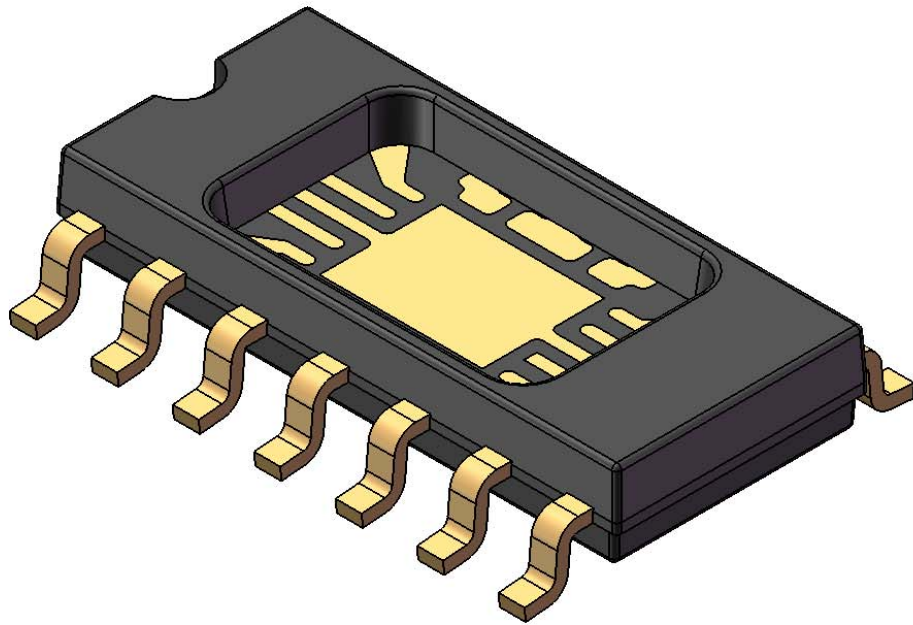
BOND DIAGRAM



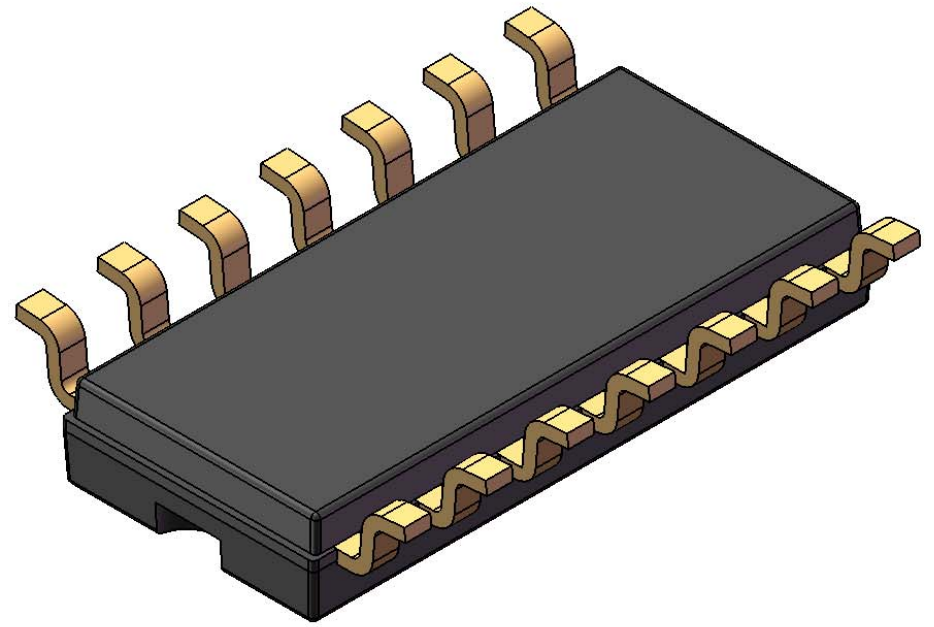
			
TITLE SOIC 14LD PITCH 1.27 MM OPEN CAVITY PACKAGE			
SCALE 20:1	SIZE A	DRAWING NO. 120114	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODEL

TOP



BOTTOM



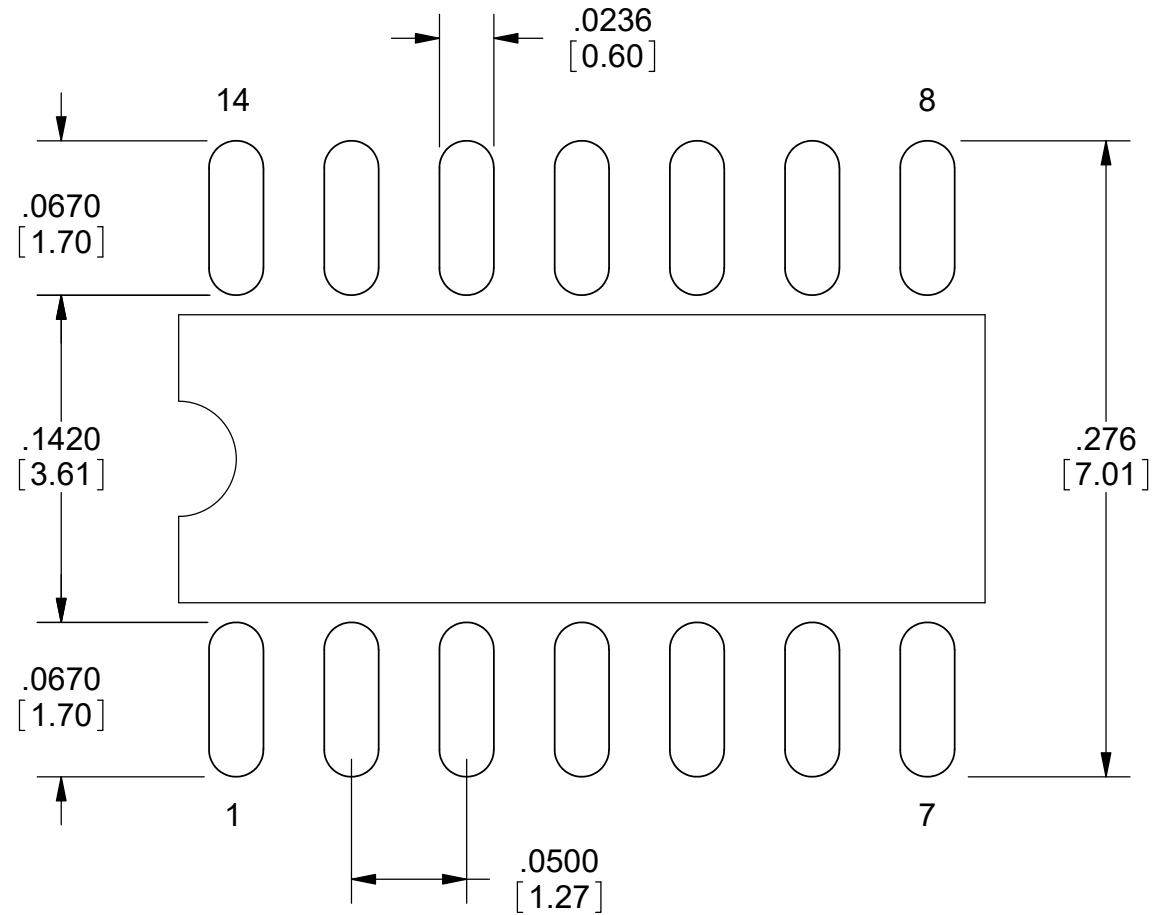
TITLE SOIC 14LD PITCH 1.27 MM
OPEN CAVITY PACKAGE

SCALE 12:1	SIZE A	DRAWING NO. 120114	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 4

SUGGESTED PCB
LAND PATTERN



TITLE SOIC 14LD PITCH 1.27 MM
OPEN CAVITY PACKAGE

SCALE 12:1	SIZE A	DRAWING NO. 120114	REV A
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DO NOT SCALE DRAWING

SHEET 4 OF 4